

GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
LOK SABHA
UNSTARRED QUESTION NO.708
TO BE ANSWERED ON: 07.02.2024

MOU BETWEEN INDIA AND EU

708. SHRI DAYANIDHI MARAN:

Will the Minister of ELECTRONICS AND INFORMATION TECHNOLOGY be pleased to state:

- (a) the details of the objectives of the Memorandum of Understanding (MoU) signed between India and the European Union regarding semiconductor research and innovation;
- (b) the details of the States which have been identified for the development of semiconductor manufacturing projects along with selection criteria and reasons thereto;
- (c) the steps taken/being taken by the Government to ensure the effective implementation of the MoU and how does this agreement fit into the broader efforts of the Ministry of Electronics and Information Technology to foster a conducive environment for electronics manufacturing in the country;
- (d) whether the MoU align with India's broader strategy for technological advancement and global collaboration in the semiconductor industry and if so, the details thereof; and
- (e) the steps taken/being taken by the Government to engage with industry stakeholders and educational institutions to facilitate talent development in the semiconductor sector?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI RAJEEV CHANDRASEKHAR)

(a) and (c): Government is very focused on its objective of building the overall semiconductor ecosystem and ensure that, it in-turn catalyses India's rapidly expanding electronics manufacturing and innovation ecosystem. Government has approved Semicon India programme with a total outlay of INR 76,000 crore for the development of semiconductor and display manufacturing ecosystem in the country. The programme aims to provide financial support to companies investing in semiconductors, display manufacturing and design ecosystem. This paves the way for India's growing presence in the global electronics value chains.

An MoU has been signed between India and the European Commission on 21 November 2023 on "Working arrangements on Semiconductors ecosystem, its supply chain and innovation under the framework of EU-India Trade and Technology Council (TTC)". This MoU intends to enhance bilateral collaboration to boost the resilience of the semiconductor supply chains and leverage complementary strengths to promote collaboration in the field of semiconductors. Government of India is making significant efforts to achieve the objectives under this MoU.

(b): The decision regarding the location of chip manufacturing facility lies with companies proposing to setup such facilities. The parameters which affect the selection of manufacturing site for semiconductor manufacturing facility, inter alia, includes: availability of uninterrupted and stable power supply, sufficient water supply, availability of land in Close Proximity to the Airport, dedicated policy for semiconductors, State Government incentives, cluster approach and supportive ecosystem, availability of social infrastructure, and manpower, State Government industry promotion activities, ease of doing business.

(d): Yes Sir, the MoU signed between India and European Commission is aligned with country's strategies for technological advancement and global collaboration in the semiconductor industry that can encompass the exchange of experiences and best practices regarding semiconductor strategies, programs, trade barriers, and disruptions, with a focus on potential measures to mitigate these challenges. This builds a trusted semiconductor supply chain across the world.

(e): The steps taken by the Government to engage with industry stakeholders and educational institutions to facilitate talent development in the semiconductor sector:

- i. **Talent Development:** Recognizing the importance of Talent development in Semiconductor domain, a technology intensive sector, Government of India has been making significant efforts to develop India as a global talent hub for semiconductors. New curriculums have been launched at UG, Diploma level as a step towards creation of Talent pool in Semiconductor design and Manufacturing domain.
- ii. **Chips to Start-up (C2S) Programme** has also been initiated with an outlay of Rs 250 Crore for a duration of 5 Years. C2S Programme aims to train 85,000 number of industry-ready manpower specialized in the area of VLSI/ Chip design/ Embedded System Design and leapfrog in ESDM space by way of inculcating the culture of Chip/ System-on-Chip (SoC)/ System Level Design at B.Tech, M.Tech & PhD level and act as catalyst for growth of Start-ups involved in semiconductor design in the country.
- iii. **MoU with Purdue University, USA** has been signed by India Semiconductor Mission (ISM), Ministry of Electronics and Information Technology for skilled workforce development and joint R&D in the broad field of semiconductors and microelectronics.
- iv. **MoU with IBM India Private Limited** has been signed by India Semiconductor Mission (ISM), Ministry of Electronics and Information Technology to establish IBM as a flagship knowledge partner of ISM for the Research Centre including Framework, R&D, Skills Development, Archetypal Chip Design, Investment/Funding support, Business development etc.
- v. Further, Government conducts regular Digital India Dialogue with all stakeholders to get inputs on policies, institutional design etc.
